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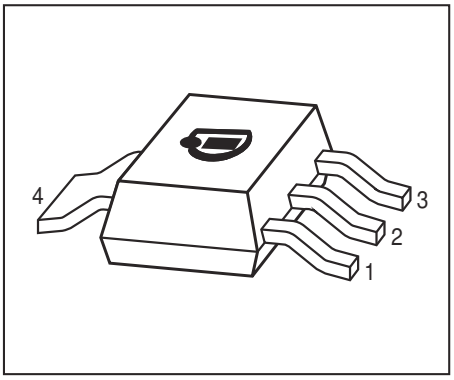
NPN Silicon RF Transistor*



- For low noise, high-gain amplifiers up to 2 GHz
- For linear broadband amplifiers
- f_T = 8 GHz, F = 1 dB at 900 MHz
- Pb-free (RoHS compliant) package[1)]
- Qualified according AEC Q101

* Short term description

AEC Qualified RoHS

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFG193	BFG193	1 = E	2 = B	3 = E	4 = C	-	-	SOT223

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	12	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	80	mA
Base current	I_B	10	
Total power dissipation[2)] $T_S \leq 87°C$	P_{tot}	600	mW
Junction temperature	T_j	150	°C
Ambient temperature	T_A	-55 ... 150	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[3)]	R_{thJS}	≤ 105	K/W

[1]Pb-containing package may be available upon special request

[2]T_S is measured on the collector lead at the soldering point to the pcb

[3]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

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Electrical Characteristics at T_A = 25°C, unless otherwise specified

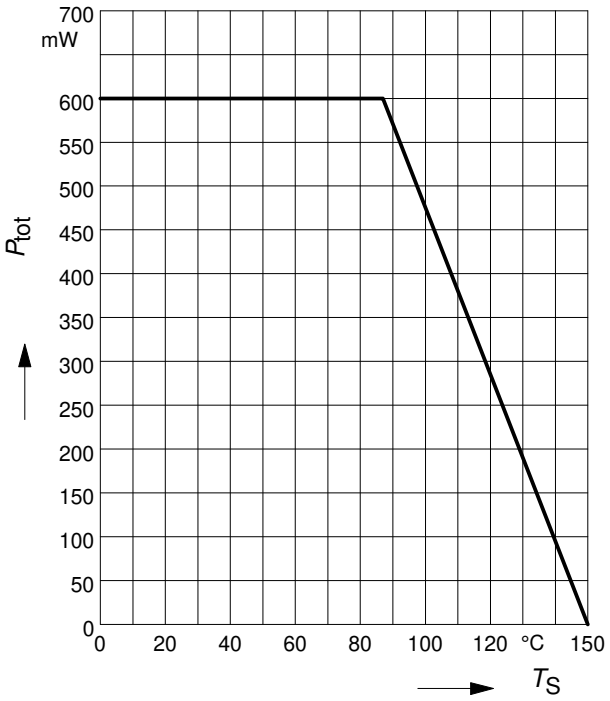
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 1 mA, I_B = 0	$V_{(BR)CEO}$	12	-	-	V
Collector-emitter cutoff current V_{CE} = 20 V, V_{BE} = 0	I_{CES}	-	-	100	µA
Collector-base cutoff current V_{CB} = 10 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 1 V, I_C = 0	I_{EBO}	-	-	1	µA
DC current gain- I_C = 30 mA, V_{CE} = 8 V, pulse measured	h_{FE}	70	100	140	-

Electrical Characteristics at T_A = 25°C, unless otherwise specified

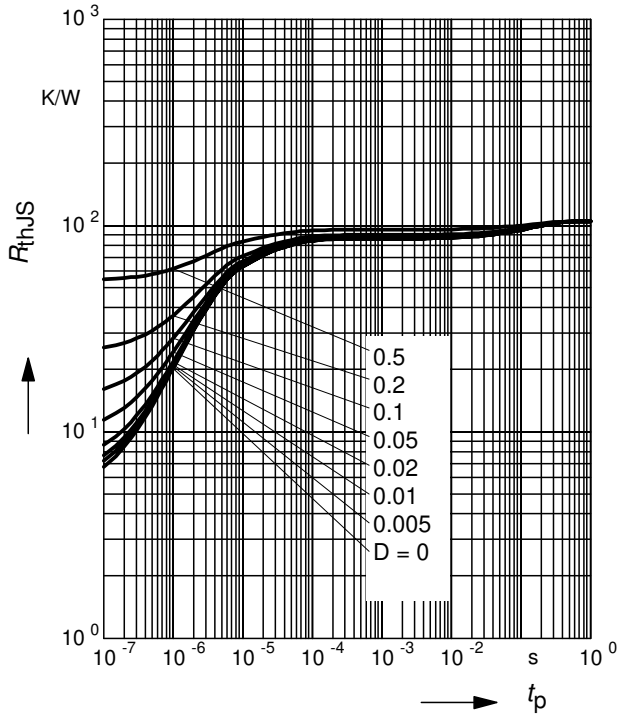
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency I_C = 50 mA, V_{CE} = 8 V, f = 500 MHz	f_T	6	8	-	GHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz, V_{BE} = 0 , emitter grounded	C_{cb}	-	0.59	0.9	pF
Collector emitter capacitance V_{CE} = 10 V, f = 1 MHz, V_{BE} = 0 , base grounded	C_{ce}	-	0.4	-	
Emitter-base capacitance V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded	C_{eb}	-	2.5	-	
Noise figure I_C = 10 mA, V_{CE} = 8 V, Z_S = Z_{Sopt} , f = 900 MHz I_C = 10 mA, V_{CE} = 8 V, Z_S = Z_{Sopt} , f = 1.8 GHz	F	 - -	 1 1.6	 - -	dB
Power gain, maximum available[1)] I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_{Sopt} , Z_L = Z_{Lopt} , f = 900 MHz I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_{Sopt} , Z_L = Z_{Lopt} , f = 1.8 GHz	G_{ma}	 - -	 16 10.5	 - -	
Transducer gain I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_L = 50Ω , f = 900 MHz I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_L = 50Ω , f = 1.8 GHz	$\lvert S_{21e}\rvert^2$	 - -	 13.5 8	 - -	dB

[1] $G_{ma} = |S_{21} / S_{12}| (k-(k^2-1)^{1/2})$

Total power dissipation $P_{tot} = f(T_S)$

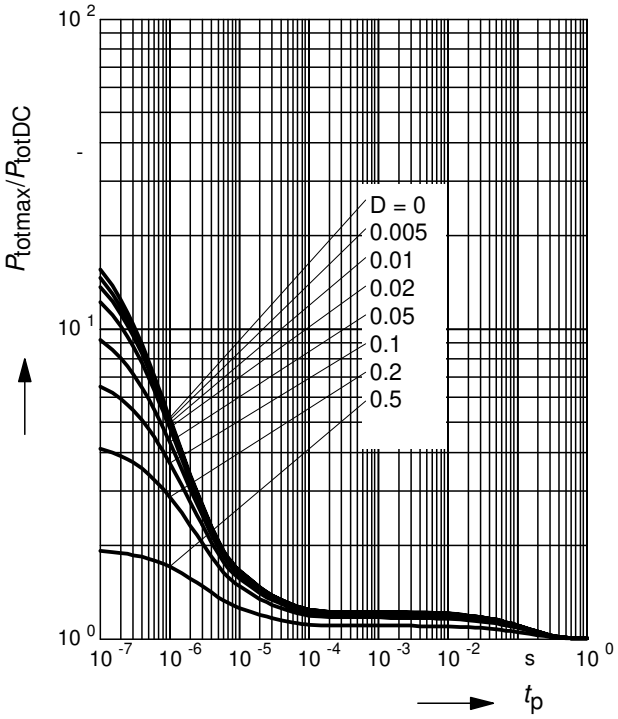


Permissible Pulse Load $R_{thJS} = f(t_p)$



Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$



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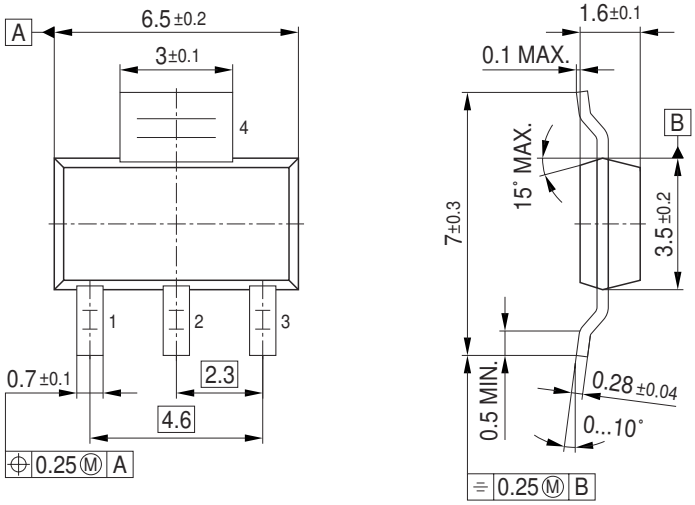
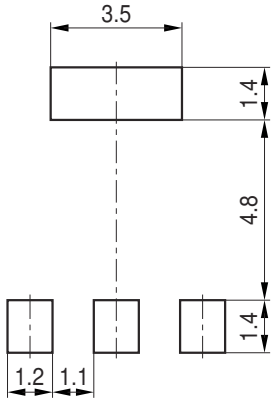
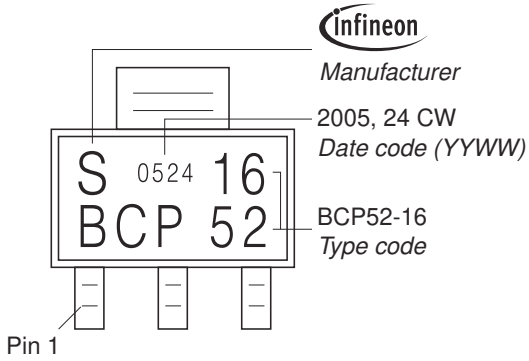
Package Outline



Foot Print

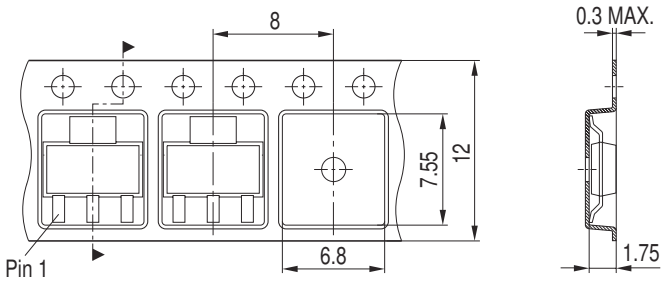


Marking Layout (Example)



Packing

Reel ø180 mm = 1.000 Pieces/Reel
Reel ø330 mm = 4.000 Pieces/Reel



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